

Final Product/Process Change Notification

Document #:FPCN23660XI Issue Date:19 Jan 2024

Title of Change:	Wafer Fab Site Addition of onsemi, Aizu Japan as an Alternate Fab Site for ONC25BCD		
Proposed First Ship date:	26 Apr 2024 or earlier if approved by customer		
Contact Information:	Contact your local onsemi Sales Office or Jonathan.Bass@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local onsemi Sales Office or Jacob.Saliba@onsemi.com		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com		
Marking of Parts/ Traceability of Change:	No change to marking / Changed material may be identified by date code		
Change Category:	Wafer Fab Change		
Change Sub-Category(s):	Manufacturing Site Addition		
Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	
onsemi Aizu, Japan		None	

Description and Purpose:

onsemi would like to inform its customers that it has qualified an additional wafer fab.

The wafer technology was previously qualified in 2021 and multiple products are already running production on this flow. These changes can be found under FPCN23660 series.

Upon expiration of this FPCN, all products listed can be manufactured in Gresham or Aizu Fab.

	From	То	
Fab Site	onsemi Gresham, US	onsemi Gresham, US or onsemi Aizu, Japan	

There will be no change to the orderable part number.

There will be no product marking change as a result of this change.

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Reliability Data Summary:

QV DEVICE NAME: NCP81206MNTXG

RMS: **029583**

PACKAGE: QFN52 6x6

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre TC, uHAST, HAST for surface mount pkgs only		0/693
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Resistance to Solder Heat	JESD22- B106	Ta = 260°C, 10 sec Required for through hole devices only		0/90

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.

Part Number	Qualification Vehicle
NCP81233MNTXG	NCP81206MNTXG

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